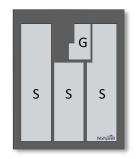
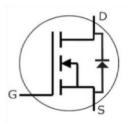


Wolfspeed SiC Gen 3 MOSFET

Description

This is the Wolfspeed's 3rd generation of high performance silicon carbide MOSFET in a packageless bare die format to be implemented into any custom module design. The high blocking voltage with low on-resistance, high speed switching with low capacitance make this MOSFET ideal for high frequency switching application including solar inverters and EV chargers.





Package Types: Bare Die PN's: CPM3-1200-0021A

Features

- Enhanced 3rd Generation SiC MOSFET
- High blocking voltage with low on-resistance
- High speed switching with low capacitance
- Fast intrinsic diode with low reverse recovery

Applications

- Motor Drive
- Solar Inverters
- SMPS
- High voltage DC/DC converters

Absolute Maximum Ratings

Stress beyond those listed under absolute maximum ratings may damage the device.

arameter Symbol			Rating	Unit
Drain-Source Voltage, across T _{vj}	V _{DS} (max)		1200	V
Maximum Gate-Source Voltage, Peak Transient Capability	V _{GS(max)}		-8/+19	V
Continuous Drain Current, V _{GS} = 15V, assumes die packaged in	lp	$T_c = 25^{\circ}C$	100	_
TO-247 package with R _{th(j-c)} < 0.32 K/W		$T_c = 100$ °C	74.5	A
Pulsed Drain Current, tp limited by Tvj(max)			200	A
Firtual Junction and Storage Temperature TvJ, Tstg			-55 to 175	°C
Maximum Processing Temperature, in non-reactive ambient			325	°C

Recommended Operating Conditions

Parameter	Symbol	Rating	Unit
Recommended Operating Gate - Source Voltage	V _G S(op)	-4/+15	V

Electrical Characteristics (T_{VJ} = 25°C)

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	V _{(BR)DSS}	1200			V	$V_{GS} = 0 \text{ V}, I_D = 100 \mu\text{A}$
Gate Threshold Voltage	V _{GS(th)}	1.8	2.5	3.6	V	V _{DS} = V _{GS} , I _{DS} = 16.8 mA
			2		V	V _{DS} = V _{GS} , I _{DS} = 16.8 mA, T _{VJ} = 175°C
Zero Gate Voltage Drain Current	IDSS		1	25	μΑ	V _{DS} = 1200 V, V _{GS} = 0 V
Gate-Source Leakage Current	Igss		10	100	nA	V _{GS} = 15 V, V _{DS} = 0 V
Drain-Source On-State Resistance	R _{DS} (on)	14.5	21	27	mΩ	V _{GS} = 15 V, I _D = 61 A
			38			V _{GS} = 15 V, I _D = 61 A, T _{VJ} = 175°C
Transconductance	gfs		35		- S	V _{DS} = 20 V, I _{DS} = 61 A
			33			V _{DS} = 20 V, I _{DS} = 61 A, T _{VJ} = 175°C
Input Capacitance	Ciss		4818			V 0V V 1000 V
Output Capacitance	Coss		180		pF	$V_{GS} = 0 \text{ V}, V_{DS} = 1000 \text{ V}$ f = 100 kHz
Reverse Transfer Capacitance	Crss		12			V _{AC} = 25 mV
Coss Stored Energy	E _{oss}		99		μJ	V _{DS} = 1000 V, f = 100 kHz
Internal Gate Resistance	R _{G(int)}		3.3		Ω	f = 100 kHz, V _{AC} = 25 mV
Gate to Source Charge	Q_{gs}		49			V _{DS} = 800 V, V _{GS} = -4 V/15 V
Gate to Drain Charge	Q _{gd}		50		nC I _{DS}	I _{DS} = 61 A
Total Gate Charge	Qg		162			Per IEC60747-8-4 pg 21

Reverse Diode Characteristics (T_{VJ} = 25 °C)

Characteristics	Symbol	Тур.	Max.	Unit	Test Conditions	
Diode Forward Voltage	VsD	4.6		V	$V_{GS} = -4 \text{ V}, I_{SD} = 30.5 \text{ A}$	
		4.2		V	$V_{GS} = -4 \text{ V}, I_{SD} = 30.5 \text{ A}, T_{VJ} = 175 ^{\circ}\text{C}$	
Reverse Recovery Time	trr	34		ns	$V_{GS} = -4 \text{ V}, I_{SD} = 61 \text{ A}, V_R = 800 \text{ V}$ $dif/dt = 2600 \text{ A}/\mu\text{s}, T_{VJ} = 175 \text{ °C}$	
Reverse Recovery Charge	Qrr	928		nC		
Peak Reverse Recovery Current	Irrm	42		Α		

Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

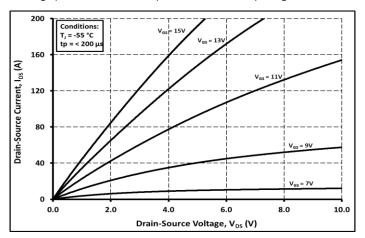


Figure 1.

Output Characteristics T_{vj} = -55 °C

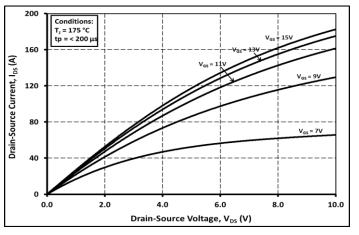


Figure 3.

Output Characteristics T_{vj} = 175 °C

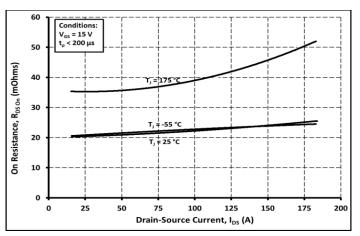


Figure 5.

On-Resistance vs. Drain Current For Various Temperatures

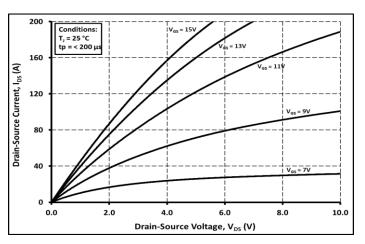


Figure 2.

Output Characteristics $T_{vj} = 25$ °C

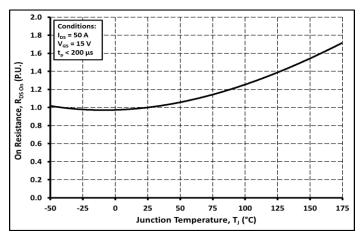


Figure 4.

Normalized On-Resistance vs. Temperature

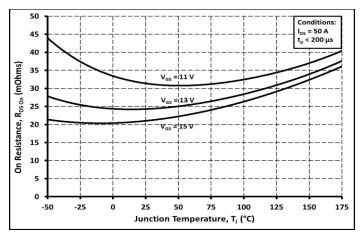


Figure 6.

On-Resistance vs. Temperature For Various Gate Voltages

Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

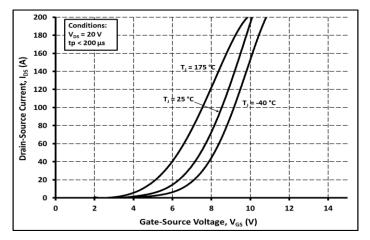
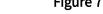


Figure 7.



Transfer Characteristic For Various Junction Temperatures

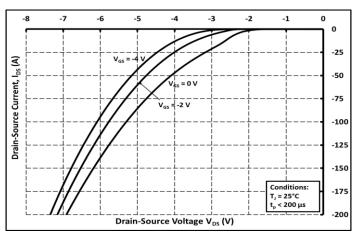


Figure 9.

Body Diode Characteristic at T_{vj} = 25 °C

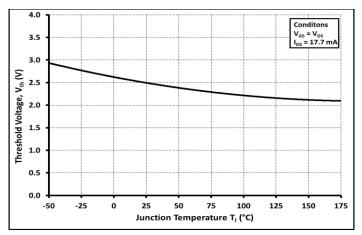


Figure 11.

Threshold Voltage vs. Temperature

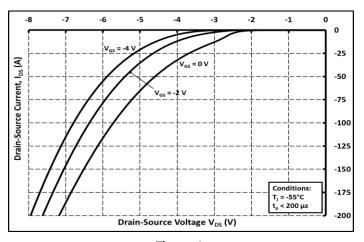


Figure 8.

Body Diode Characteristic at T_{vj} = -55 °C

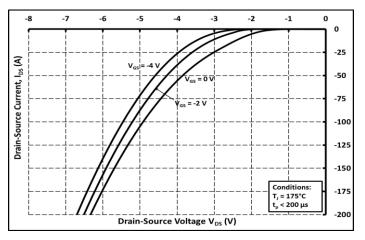


Figure 10.

Body Diode Characteristic at T_{vj} = 175 °C

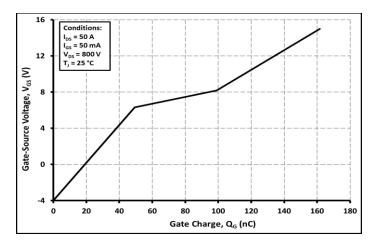


Figure 12.

Gate Charge Characteristics

Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

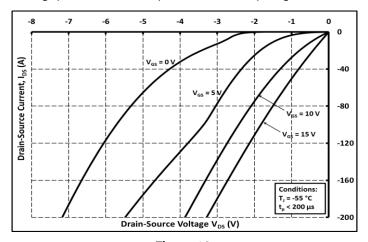


Figure 13.

3rd Quadrant Characteristic at T_{vj} = -55 °C

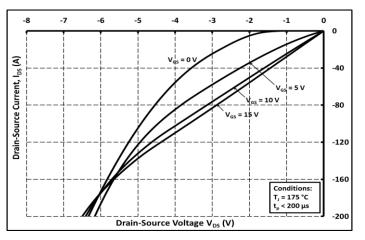


Figure 15.

3rd Quadrant Characteristic at T_{vj} = 175 °C

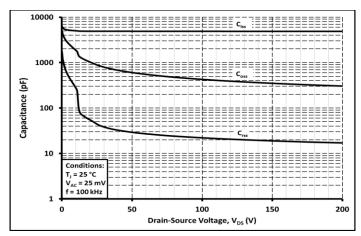


Figure 17.

Capacitances vs. Drain-Source Voltage (0-200V)

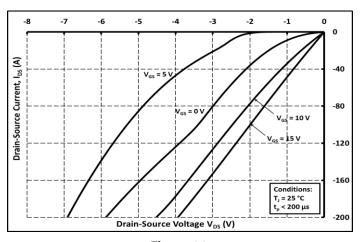


Figure 14.

3rd Quadrant Characteristic at T_{vj} = 25 °C

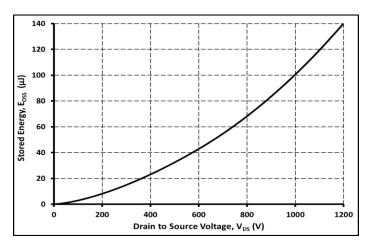


Figure 16.

Output Capacitor Stored Energy

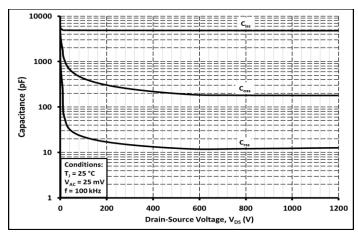


Figure 18.

Capacitances vs. Drain-Source Voltage (0-1200V)

Product Ordering Information

Order Number	Description	Package
CPM3-1200-0021A-FY6	SIC MOSFET G3 IND 1200V/21mO UV MLT	Bare Die Product
CPM3-1200-0021A-GQ8	SIC MOSFET G3 IND 1200V/21mO UV MVF	Bare Die Product

Revision History

Revision History	Date of Change	Brief Summary
-	04/04/2019	Initial Release
1	01/09/2020	 Removed test conditions and note section from the Maximum Ratings Table Updated description for all the parameters in the Maximum Ratings Table Updated footnotes Temperature note removed and embedded into every test condition Updated test conditions for gate threshold voltage, drainsource on-state resistance, transconductance, gate to source charge, gate to drain charge, total gate charge, diode forward voltage, reverse recovery time, reverse recovery charge and peak reverse recovery current Updated typical values for continuous drain current, zero gate voltage drain current, gate-source leakage current, drain-source on-state resistance, transconductance, input capacitance, reverse transfer capacitance, Coss stored energy, gate to source charge, gate to drain charge, total gate charge, reverse recovery time and reverse recovery charge All junction temperatures changed to virtual junction temperatures All graphs updated to reflect the most recent test data
2	07/30/2023	Document format updated
3	07/09/2024	Updated die image on the first page

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